

KB-3151S (ANSI : FR-1/JIS : PP7F)

覆銅箔酚醛樹脂紙基層壓板

特點

- 在高溫下彎曲率、扭曲率小於 1.0%
- 潮濕環境下電氣性能優良
- 適合銀漿灌孔雙面線路板

Features

- In high temperature warpage and twist both less than 1.0%
- Superior electric properties under moisture condition
- Suitable for double side application by silver through hole

General Properties 一般特性

Test Item 測試項目	Unit 單位	Test Condition 處理條件	Testing Method 測試方法	Specification 規格值	Typical Value 典型值
Solder Resistance 耐浸焊性(260℃)	Sec	A	JIS C 6481	≥10	20~30
Heat Resistance 耐熱性	---	130℃ 30min	JIS C 6481	No Change 無異常	No Change 無異常
Peel Strength(Copper Foil 35 μm) 銅箔剝離強度(35 μm 銅箔)	Kgf/cm	A 260℃/5Sec	JIS C 6481	≥1.2	1.8~2.1 1.7~2.0
Flexural Strength 屈曲強度	Lengthwise 縱向	A	JIS C 6481	≥8	15~17
	Crosswise 橫向			≥8	14~15
Volume Resistivity 體積阻抗係數	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	5×10 ⁹ 5×10 ⁸	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹² ~10 ¹³
Surface Resistance 表面抗阻	Adhesive Side 粘接劑面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹⁰ 1×10 ⁹	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹⁰ ~10 ¹¹
	Laminate Side 積層板面			C-96/20/65 C-96/20/65+C-96/40/90	1×10 ⁹ 1×10 ⁷
Insulation Resistance 絕緣抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ⁹ 1×10 ⁶	1.0×10 ¹² ~10 ¹³ 1.0×10 ¹⁰ ~10 ¹¹
Chemical Resistance 耐化學性	---	3% NaOH 40℃ 3min 3%氫氧化鈉 40℃ 3分鐘	JIS C 6481	No change 無異常	No Change 無異常
		Boild in trichloroethylene for 3 min 三氯乙炔中煮沸 3分鐘	JIS C 6481	No change 無異常	No Change 無異常
Water Absorption 吸水性	%	E-24/50+D-24/23	JIS C 6481	≤2	0.6~0.8
Flammability 阻燃性	Sec	A	UL94	94V-0	V-0
Dielectric Constant (1 MHz) 介電常數	---	C-96/20/65	JIS C 6481	≤5.5	4.0~5.0
		C-96/20/65+D-24/23		≤6.0	4.5~5.5
Dissipation Factor 介質損耗因數	---	C-96/20/65	JIS C 6481	≤0.05	0.025~0.035
		C-96/20/65+D-24/23		≤0.1	0.025~0.045
CTI Value CIT 值	V	0.1% NH ₄ Cl	IEC 112	---	>250
Punching Temperature 沖孔溫度	℃	A	WI-QA-002	50~70	室溫~70

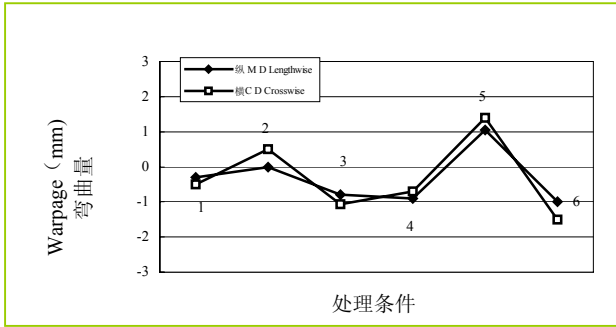
Remarks : Typical values for reference only 注：典型值只作參考 Stand values according to JIS-C-6485 規格值參照 JIS-C-6485

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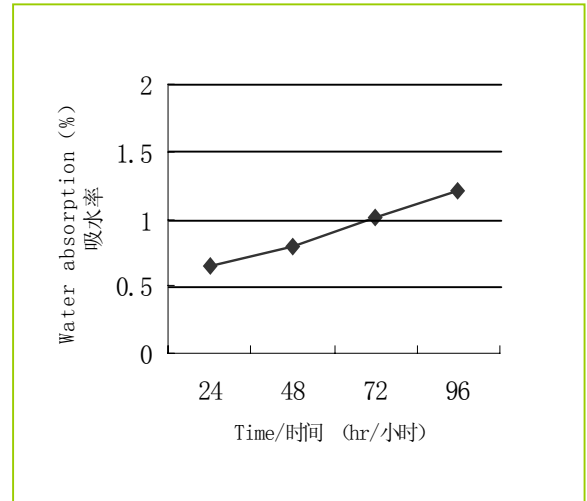
Speciality Chart 板材特性圖

Warpage of PCB during processing/印製電路板
加工時彎曲度(Thickness 1.6mm single side)

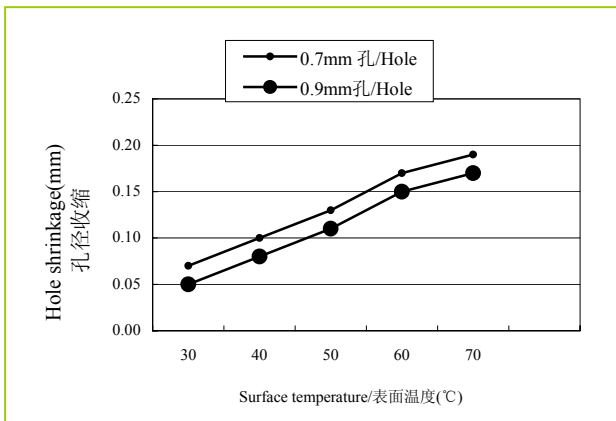


1. Feeding 投料	2. Heating at 130°C for 90 sec 130°C下加熱90秒	3. Etching, Rinsing, Drying 蝕刻, 清洗, 烘乾
4. Heating at 200°C for 30 sec 200°C下加熱30秒	5. Punching at 50°C 50°C下沖孔	6. Soldering at 260°C for 5 sec 260°C 焊錫5秒

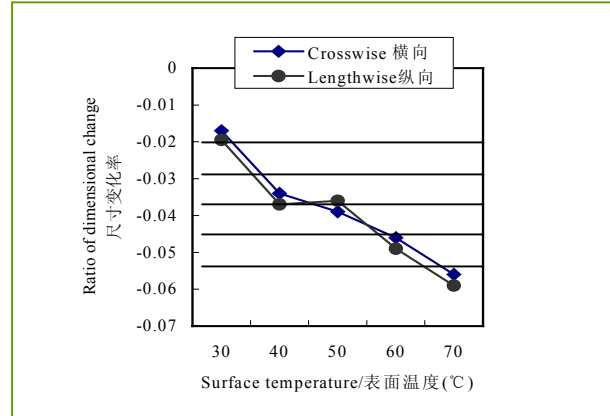
Water absorption 吸水率



Punched hole shrinkage
沖孔後孔徑收縮



Dimensional change of punched PCB
沖孔後之尺寸變化



Purchasing Information / 採購資訊

Type 類型	Thickness 厚度	Copper Cladding 銅箔厚度	Regular Size (mm) 常規尺寸	CTI Value CTI 值
KB-3151S FR-1	1.0mm ~ 1.6mm	18μm 35μm 70μm	1020*1020mm (40" *40") 1020*1220mm (40" *48")	250V

Note: Other sheet size and thickness could be available upon request.

可根據客戶要求提供其他尺寸和厚度。